

DS Tested

**; YbYfU`8YgWf]dh]cb`**

Split gate trench MOSFET technology  
Excellent package for heat dissipation  
High density cell design for low  $R_{DS(ON)}$   
Moisture Sensitivity Level 1  
Epoxy Meets UL 94 V-0 Flammability Rating  
Halogen Free  
Part no. with suffix "Q" means AEC-Q101 qualified

**5dd`]WUh]cbg`**

Power switching application  
Uninterruptible power supply  
DC-DC convertor

**5Vgc`ihY`AUI]aia`FUh]b[g`**( $T_J=25$  unless otherwise noted)

DUfUaYhYf`



M>6)8\$; \$\* <E'

9`YWhf]WU`7 \UfUWhYf]gh]Wg' (T<sub>J</sub>=25 unless otherwise noted)

DUfU a YhYf'	Gm a Vc''	7cbX]h]cbg'	A]b'	Hmd'	AUI'	I b]hg'
GhU]W'DUfU a YhYf'						

**M>6) 8\$; \$\* <E'**

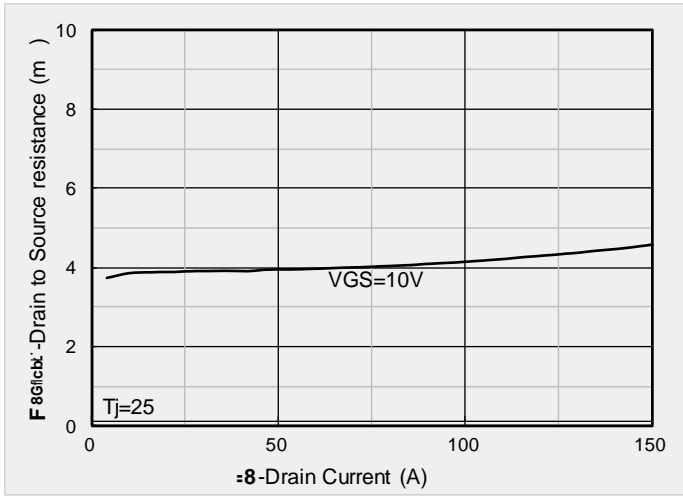


Figure 7: RDS(on) VS Drain Current

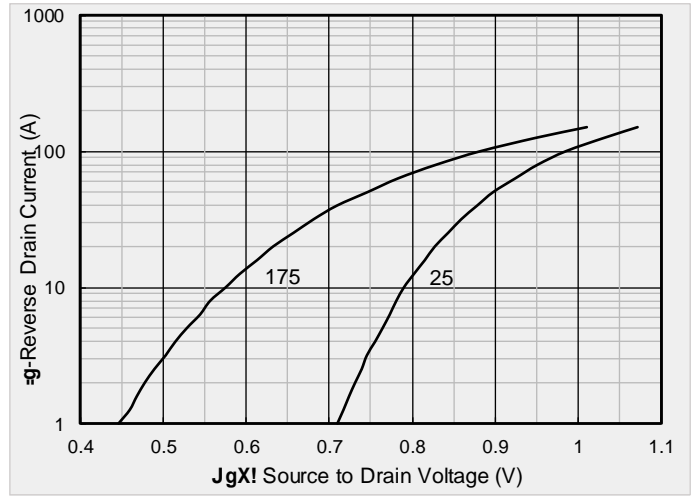


Figure 8: Forward characteristics of reverse diode

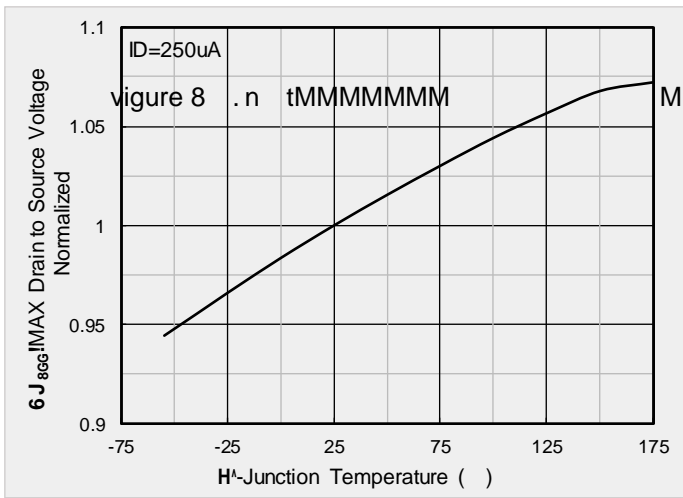


Figure 9: Normalized Drain-Source Voltage vs Junction Temperature

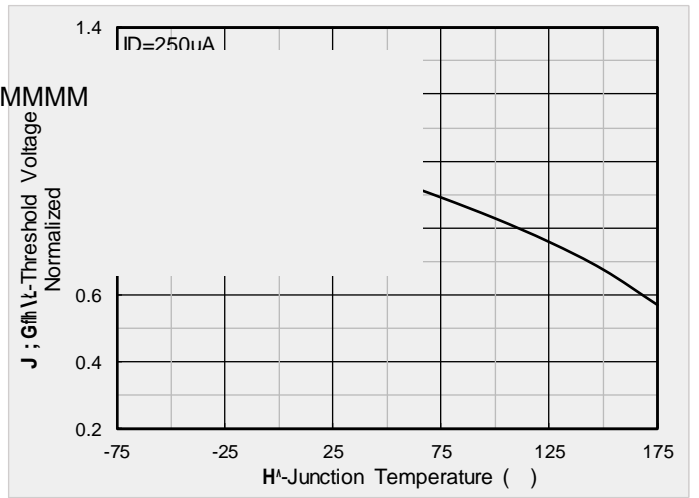
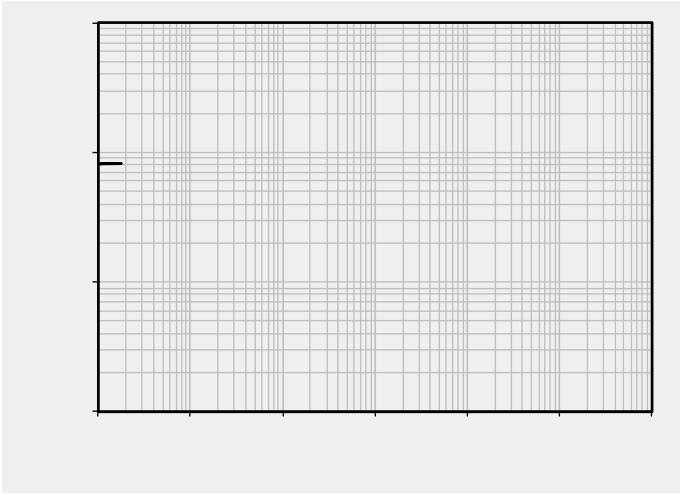


Figure 10: Normalized Vth vs Junction Temperature

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HC!&\* '!<M'DUW\_U[Y']bzcf a Uh]cb

SYMBOL	MIN.	
	A2	0.000
b2		0.050
c		
c2		
D2		
E		
E1		

'LVFODLPHU

7KH LQIRUPDWLRQ SUHVHQWHG LQ WKLV <DQJ> KRXVH QDWQV MIRHU (WHIHFWURQ EFRQHFHQW ROR  
ULJKW WR PDNH FKDQJH RU ZWLVK RXSWKH R SAURVGLFQV RIGWVSOD\HG KHUHLQ WRGLHPSLURQY  
RWKHU ZLVH

7KH SURGXFW OLVWJH EHWURLEH LXV B EHZLWHKF WXURRERW DYRUQRWHGLQV E JHGH FDO OLIH  
VDYLQJ OLIVXVWD <DQJ> R UODLQD QHD R QXPMV ERKU DLSREQOLELQRW \DQJGQPDUR  
VXFK LPSURSHU XVH RI VDOH

7KLV SXEOLF DWLRQ SVKSHUW DQDVLQURQ PDVLSRQLSHGHYRUR XDVGLRQLRSDODVLRWHUPLWWRSX  
ZZZ \DQJMLHRURPRQVXOW \RXUH QHD DQJWR B DQJWKWDQFH